

Advanced IC Substrate Market: Global Industry Trends, Share, Size, Growth, Opportunity and Forecast 2023-2028

Market Report | 2023-05-29 | 148 pages | IMARC Group

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Report description:

Market Overview:

The global advanced IC substrate market size reached US\$ 9.4 Billion in 2022. Looking forward, IMARC Group expects the market to reach US\$ 13.8 Billion by 2028, exhibiting a growth rate (CAGR) of 6.2% during 2023-2028.

Advanced integrated circuit (IC) substrate is a baseboard used to connect the printed circuit boards (PCBs) to the semiconductor chips. It is compact, durable, lightweight, energy-efficient, and cost-effective and exhibits high thermal dissipation performance. In addition, it provides high reliability and outstanding electrical properties, reduces the overall weight of PCBs, and increases their functionality and dimensional control. As a result, it is currently widely used for manufacturing miniaturized electronic products with the latest functions.

Advanced IC Substrate Market Trends:

The escalating demand for miniaturized consumer electronic products, such as tablets, laptops, smartphones, and personal computers (PCs), represents one of the key factors impelling the market growth. Moreover, the rising need for remote-controlled electrical equipment in industrial applications is contributing to the market growth. Apart from this, defense departments in various countries rely on several microelectronics, such as nuclear-armed bombers, submarines, intercontinental ballistic missiles, and space-based sensors, to make deterrence strategies that protect deployed forces, allies, and partners. Furthermore, as sensitive microelectronics are vulnerable to high levels of ionizing radiation, defense agencies are deploying advanced IC substrates to protect them in hazardous conditions. Besides this, a wide range of applications of handheld, portable, and implantable medical electronic devices in the diagnosis and treatment of various critical diseases is catalyzing the demand for advanced IC substrates in the healthcare industry. In line with this, the growing trend of cars with driverless and safety features and innovative infotainment systems are contributing to the adoption of advanced IC substrates in the automotive industry. This

can also be accredited with efforts undertaken by governing agencies of numerous countries to promote green, electric vehicles (EVs) and minimize greenhouse (GHG) emissions of automobiles.

Key Market Segmentation:

IMARC Group provides an analysis of the key trends in each sub-segment of the global advanced IC substrate market report, along with forecasts at the global, regional and country level from 2023-2028. Our report has categorized the market based on type and application.

Breakup by Type:

□FC BGA □FC CSP

Breakup by Application:

Consumer Electronics
 Automotive and Transportation
 IT and Telecom
 Others

Breakup by Region:

North America Π □□United States ∏∏Canada Π □Asia-Pacific Π []China □□Japan ∏∏India South Korea □□Australia □□Indonesia **□Others** Π [Europe Π [][Germany **□□**France United Kingdom Italy Ostal []]Russia □□Others

Latin America
Latin America
Brazil
Mexico
Others
Middle East and Africa
Competitive Landscape:

The competitive landscape of the industry has also been examined along with the profiles of the key players being ASE Group, AT & S Austria Technologie & Systemtechnik Aktiengesellschaft, Fujitsu Limited, Ibiden Co. Ltd., JCET Group Co. Ltd, Kinsus Interconnect Technology Corp., Korea Circuit Co. Ltd., KYOCERA Corporation, LG Innotek Co. Ltd., Nan Ya PCB Co. Ltd. (Nan Ya Plastics Corporation), TTM Technologies Inc. and Unimicron Technology Corporation (United Microelectronics Corporation).

Key Questions Answered in This Report:

How has the global advanced IC substrate market performed so far and how will it perform in the coming years?
What has been the impact of COVID-19 on the global advanced IC substrate market?
What are the key regional markets?
What is the breakup of the market based on the type?
What is the breakup of the market based on the application?
What are the key driving factors and challenges in the industry?
What is the structure of the global advanced IC substrate market and who are the key players?
What is the degree of competition in the industry?

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